

# Claims

- [c1] What is claimed is:
1. A wafer holder for semiconductor manufacturing devices, the wafer holder having a wafer-carrying surface and characterized in that the diameter  $a$  of the wafer holder wafer-carrying surface is not greater than the diameter  $b$  of the wafer holder surface on its side opposite the wafer-carrying surface.
  - [c2] 2. The wafer holder set forth in claim 1, wherein the diameter  $b$  is larger than the diameter  $a$  by 50  $\mu\text{m}$  or more.
  - [c3] 3. The wafer holder set forth in claim 1, being a ceramic susceptor interiorly in or superficially on which a resistive heating element is formed.
  - [c4] 4. The wafer holder set forth in claim 2, being a ceramic susceptor interiorly in or superficially on which a resistive heating element is formed.
  - [c5] 5. A semiconductor manufacturing device wherein the wafer holder set forth in claim 1 is installed.
  - [c6] 6. A semiconductor manufacturing device wherein the wafer holder set forth in claim 2 is installed.
  - [c7] 7. A semiconductor manufacturing device wherein the wafer holder set forth in claim 3 is installed.

[c8] 8. A semiconductor manufacturing device wherein the wafer holder set forth in claim 4 is installed.